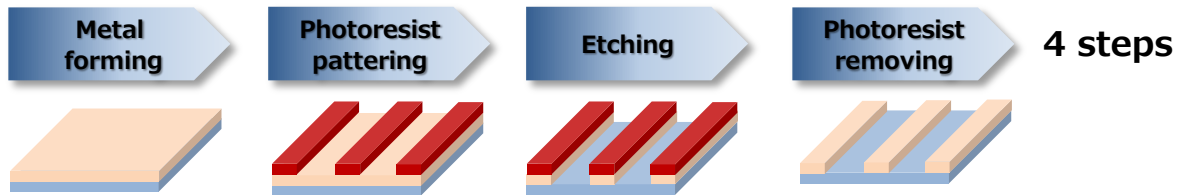


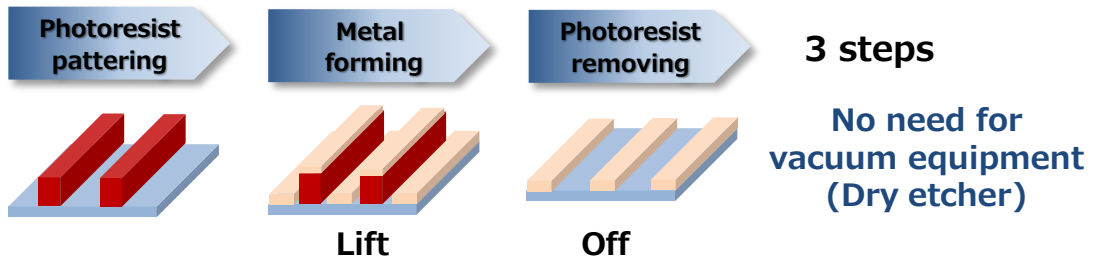
NAGASE Photoresist for Lift-off Process

Lift-off Process

Etching process (Conventional)



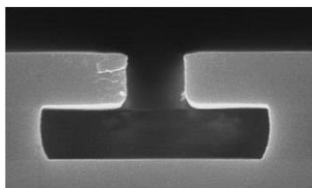
Lift-off process



Product by i-line stepper exposure (NA=0.45)

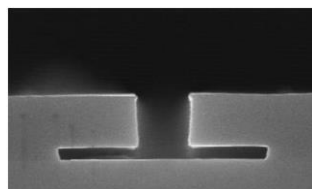
Bi-layer type

BLX series (Under layer)



0.5um trench pattern

Thickness
Upper layer : 1um
Under layer : 0.7um

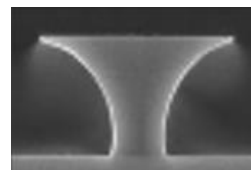


0.5um trench pattern

Thickness
Upper layer : 1um
Under layer : 0.2um

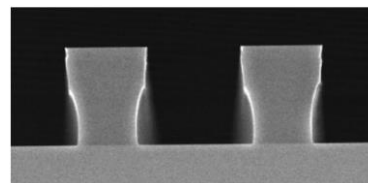
Single-layer type

NPR9700 series



10um L/S pattern

Thickness
10um



10um L/S pattern

Thickness
20um

- No intermixing
- Applicable to various upper layer
- Selectable of exposure wavelength depending on upper layer

- Positive-tone type
- Simple process
- Good step coverage
- Suitable anti-tapered profile

Customizable for customer needs